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1/31/92 7, [4.0]	6-2001	U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office
To the Honorable Commissioner of thereof.	788785	ched original documents or copy
1, Name of conveying party(ies): TAKASHI TSUCHIYA MASAMI OGATA KAZUHIKO UEDA Additional name(s) of conveying party(ies) attached? Yes No 3. Nature of conveyance: Assignment Merger Security Agreement Change of Name OtherExecution DateJuly 4 and 5, 2001 4. Application (number(s) or patent number(s): If this document is being filed together with a new	Name: Sony Con Internal Address:	nagawa 6-chome u, Tokyo 141, Japan
A. Patent Application No.(s) U.S. Serial No. 09/816,043 filed March 23, 2 Attorney Docket No. 097092909-4862 Additional numbers attached? □ Yes ☒ No	B: Patent No.	
5. Name and address of party to whom correspondence concerning document should be mailed:	7. Total Fee (37 CFR	3.41
SONNENSCHEIN NATH & ROSENTHAL P.O. Box #061080	⊠ Enclosed ⊠ Authorized to be Additional fees	charged to deposit account any
Wacker Drive Station Sears Tower Chicago, IL 60606-1080 Customer ID No. 26263	8. Deposit Account N 19.3140 (Attach duplicate copy of	
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9. Statement and signature: To the best of my knowledge and belief, the forego copy is a true copy of the original document. David R. Metzger	ing information is true a	·
Name of Person Signing Sign	nature ()	July 16, 2001 Date Total number of pages 3
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PATENT

REEL: 011995 FRAME: 0749

S01P0410US00 09792909-4862 Docket Number: _____

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name,	am a sole inventor (if
only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and usefu	il improvements in
IMAGE PROCESSING CIRCUIT AND METHOD FOR PROCESSING IMAGE	

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 09/816.043, Filing Date: 3/23/2001

This assignment executed on the dates indicated below.

TAKASHI TSUCHIYA	
Name of first or sole inventor	Execution date of U.S. Patent Application
TOKYO, JAPAN	
Residence of first or sole inventor	1
Takashi Tsuchiye	July 4, 2001
Signature of first or sole inventor	Date of this assignment

PATENT REEL: 011995 FRAME: 0750

MASAMI OGATA		
Name of second joint inventor	Execution date of U.S. Patent Application	
KANAGAWA JAPAN		
KANAGAWA, JAPAN Residence of second joint inventor	,	
Masai Bate	July 4, 2001 Date of this assignm	
Signature of second joint inventor	Date of this assignm	ent
KAZUHIKO UEDA		
Name of third joint inventor	Execution date of U.S. Patent Application	
KANACAWA TADAN		
KANAGAWA, JAPAN Residence of third joint inventor	~ ^	
Kazuhiho Ulda Signature of third joint inventor	Jul 5, 200 I Date of this assignment	
Signature of third joint inventor	Date of this assignme	enc
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Name of fourth joint inventor	Execution date of U.S. Patent Application	
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Residence of fourth joint inventor		
Signature of fourth joint inventor	Date of this assignme	nt
Jag	J.	
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Name of fifth joint inventor	Execution date of U.S. Patent Application	
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Residence of fifth joint inventor		
Signature of fifth joint inventor	Date of this assignme	nt
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